To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HVU145

Silicon Epitaxial Planar Pin Diode for High Frequency Switching

RENESAS

ADE-208-1508A (Z)

Rev.1
Jun. 2002

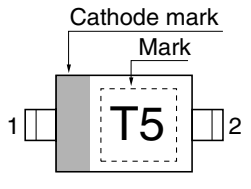
Features

- Low capacitance.(C = 0.45 pF max)
- Low forward resistance. (rf = 1.8 Ω max)
- Ultra small Resin Package (URP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVU145	T5	URP

Pin Arrangement



1. Cathode
2. Anode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	60	V
Forward current	I_F	50	mA
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_R	—	—	100	nA	V_R = 60 V
Forward voltage	V_F	—	—	0.9	V	I_F = 2 mA
Capacitance	C	—	—	0.45	pF	V_R = 1 V, f = 1 MHz
Forward resistance	r_f	—	—	1.8	Ω	I_F = 10 mA, f = 100 MHz
ESD-Capability *[1]	—	100	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

Note : 1. Failure criterion ; $I_R \geq 100$ nA at V_R = 60 V

Main Characteristic

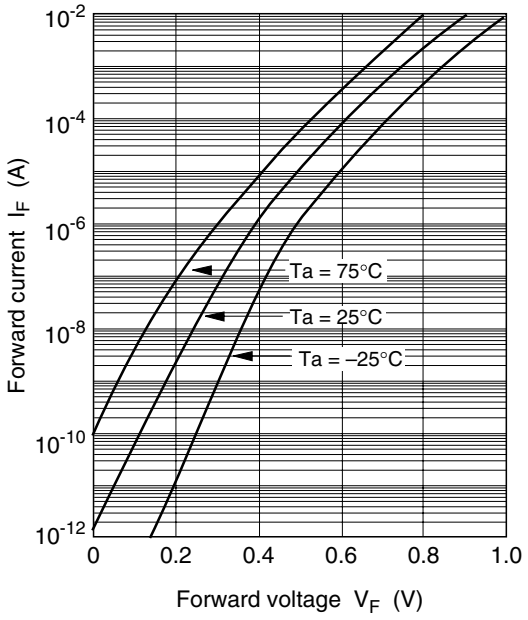


Fig.1 Forward current vs. Forward voltage

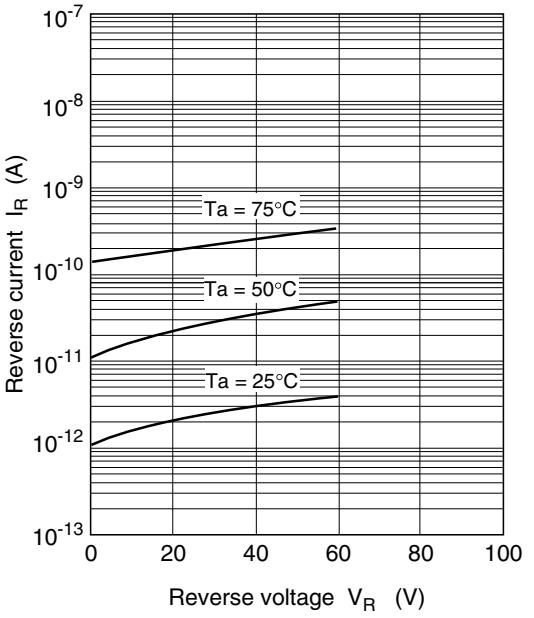


Fig.2 Reverse current vs. Reverse voltage

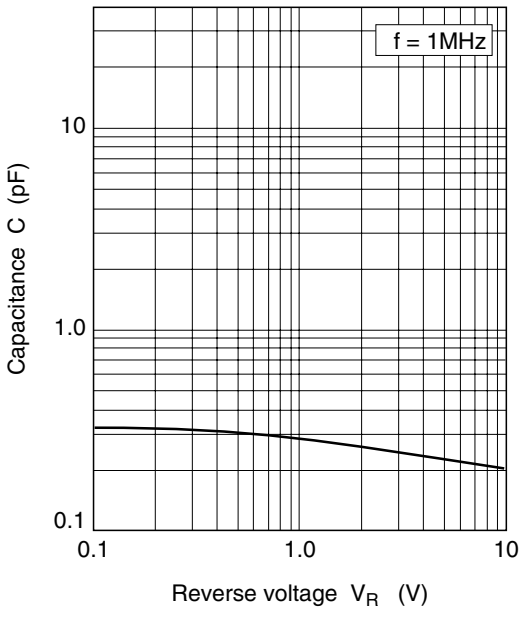


Fig.3 Capacitance vs. Reverse voltage

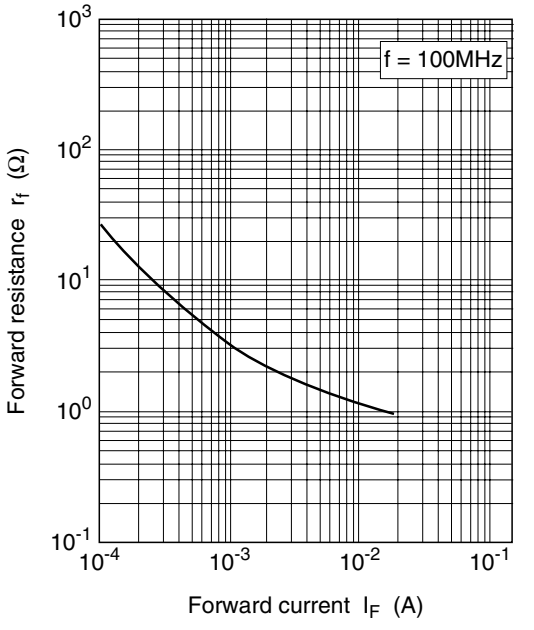


Fig.4 Forward resistance vs. Forward current

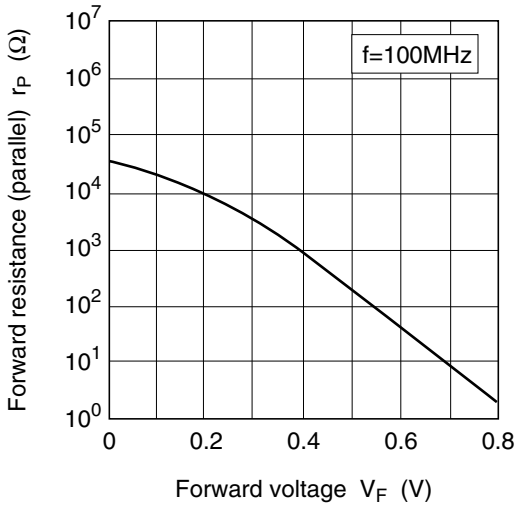
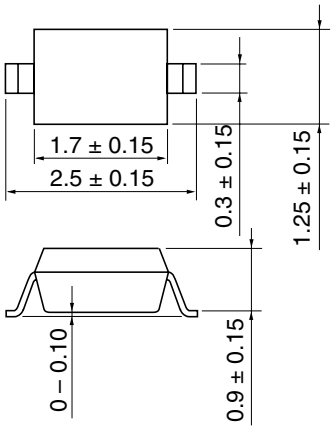


Fig.5 Forward resistance (parallel) vs. Forward voltage

Package Dimensions

As of January, 2002

Unit: mm



Hitachi Code	URP
JEDEC	Conforms
JEITA	—
Mass (reference value)	0.004 g

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